



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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OCT 29 2002

TECHNOLOGY CENTER 2800

In re the Application of:

Coyle, et al.

Docket No.: TI-31794

Serial No.: 09/992,387

Examiner: Lewis, Monica

Filed: 11/16/01

Art Unit: 2822

For: Flip-Chip on Film Assembly for Ball Grid Array Packages

Amendment under 37 CFR 1.111

Assistant Commissioner of Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the
U.S. Postal Service as First Class Mail in an envelope addressed to:
Assistant Commissioner for Patents, Washington, D.C. 20231 on

10-18-02

Jackie McBride
Jackie McBride

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 06/20/02. They are respectfully submitted as a full and complete response to that Action. A petition for a one-month extension of time is hereby made and a separate letter to that effect accompanies this paper. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.